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| Best Paper Presentation award |
| **Technical Session**  | **Best Presentation Award** | **Details** |
| Technical Session 1 | ICMAME-P-21-113**Krishnan Ganesh Kumar** | Composite Materials |
| Technical Session 2  | ICMAME-P-21-94**Priyanka** | Design, modeling and simulation, |
| Technical Session 3  | ICMAME-P-21-123**Susan G Daniel** | Industrial, Production, Energy and |
| Technical Session 4 | ICMAME-P-21-78**Abu Bakar Siddique** | Novel materials, manufacturing, |
| Technical Session 5 | IC MAME - P-2 1- 130**Tarik Hassan** | Functional Materials and Devices |
| Technical Session 6 | ICMAME-A-21-05**Navpreet Kamboj** | Oral Presentations I |
| Technical Session 7 | Paper ID: ICMAME-P-21-140**David Kumar (Taiwan)** | Thermal and Mechatronics |
| Technical Session 8 | ICMAME-P-21-60**RugmaniMeenambal** | Biomaterials and Bioengineering  |
| Technical Session 9  | ICMAME-P-21-14**Suchandra Goswami** | Nanomaterials and Nanoengineering |
| Technical Session 10 | ICMAME-P-21-72**Khushi Singh** | Smart materials, sensors, |
| Technical Session 11  | ICMAME-P-21-118**Gurpal Singh Khosa** | Advanced Structural Materials |
| Technical Session 12 | ICMAME-A-21-05**Seemesh Bhaskara** | Oral Presentation II |

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| Best Research Paper award |
| **Best Paper 1**  | **Authors: Amares Singh, Rajkumar Durairaj, K. Ganesh Kumar and Seng How Kuan**First Author Affiliations : Lee Kong Chian Faculty of Engineering and Science, UniversitiTunku Abdul Rahman, Jalan Sungai Long, Bandar Sungai Long, 43000 Kajang, Selangor, Malaysia. | Paper ID: ICMAME-P-21-111**Title of paper: Impact of 3 % Molybdenum (Mo) nanoparticles on the interfacial and shear properties of lead-free Sn58Bi/Cu solder joint.** |
| **Best Paper 2** | **Authors: Cephas Yaw Attahu, Jian Yang, Kok-Hoong Wong and Chungket Thein.**First Author Affiliations: Faculty of Science and Engineering, University of Nottingham Ningbo China, Ningbo 315100, China | *Paper ID:ICMAME-P-21-44***Title of paper: Flexural and shear strength properties of unidirectional carbon fiber reinforced polymer composite interleaved with recycled carbon fiber and short virgin aramid fiber non-woven mats** |
| **Best Paper 3** | **Authors: Krishan Kumar Chauhan, Garima Joshi, Manjeet Kaur and Renu Vig.**First Author Affiliations UIET, Panjab University, Chandigarh, India | Paper ID: ICMAME-P-21-102**Title of paper: Semiconductor Wafer Defect Classification using CNN : A Binary Case** |